


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32H753IIK6	Q2MR*450XXXV	A	9996	24-05-2019
	Amount	UoM	Unit type	ST ECOPACK Grade
	111.20	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
SOLDERBALL (Sn96.5Ag3.5)	NAC	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
BGA	10x10x0.6	201	No lead	
Comment	Package : A0E7 UFBGA 10X10X0.6 176+25 P0.65 8249558			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-15th January 2019				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	Q2MR*450XXXV				5.999999.0	0.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	4.802	mg	supplier	die	Silicon (Si)	7440-21-3		4.050	mg	845481	36511
				supplier	metallization	Aluminium (Al)	7429-90-5		0.088	mg	18326	791
				supplier	metallization	Copper (Cu)	7440-50-8		0.276	mg	57476	2482
				supplier	passivation	Nickel (Ni)	7440-02-0		0.001	mg	208	9
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.045	mg	9371	405
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	1666	72
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	208	9
				supplier	Passivation	Silicon Oxide	7631-86-9		0.323	mg	67264	2905
				supplier	CORE	Glass Cloth	65997-17-3		3.567		84900	32073
				supplier	CORE	Epoxy resin	61788-97-4		0.840		20000	7556
SUBSTRATE	M-011 Other inorganic materials	42.009	mg	supplier	CORE	Flame resistant epoxy resin	223769-10-6		0.840		20000	7556
				supplier	CORE	Heat resistant resin	25722-66-1		0.840		20000	7556
				supplier	CORE	Silica filler	7631-86-9		2.096		49900	18851
				supplier	CORE	Metal Hydroxide	Proprietary		0.210		5000	1889
				supplier	COPPER FOIL	Copper (Cu)	7440-50-8		8.389		199700	75442
				supplier	SOLDERMASK	Talc containing no asbestiform fibers	14807-96-6		0.256		6100	2304
				supplier	SOLDERMASK	Barium sulfate	7727-43-7		4.134		98400	37173
				supplier	SOLDERMASK	Dipropylene monomethyl ether	34590-94-8		1.222		29100	10993
				supplier	SOLDERMASK	Napthalene	91-20-3		0.126		3000	1133
				supplier	SOLDERMASK	Morpholine derivative	Proprietary		0.630		15000	5667
				supplier	CU PLATING	Copper (Cu)	7440-50-8		16.157		384600	145294
				supplier	NI PLATING	Nickel (Ni)	7440-02-0		2.416		57500	21722
				supplier	AU PLATING	Gold (Au)	7440-57-5		0.286		6800	2569
				DIE ATTACH	M-011 Other inorganic materials	1.267	mg	supplier	GLUE	Butadiene,acrylonitrile polymer,carboxy-termi	68610-41-3	
supplier	GLUE	Phenol-formaldehyde polymer	9003-35-4						0.127		100000	1139
supplier	GLUE	Phenol polymer with formaldehyde,glycidyl et	28064-14-4						0.117		92000	1048
supplier	GLUE	Dapsone	80-08-0						0.123		97000	1105
supplier	GLUE	Reaction product bisphenol-A-(epichlorhydrin	25068-38-6						0.013		10000	114
supplier	GLUE	4,4, Isopropylidenediphenol	80-05-7						0.001		1000	11
BONDING WIRE	M-011 Other inorganic materials	3.122	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		3.122		1000000	28079
SOLDERBALL	M-011 Other inorganic materials	6.241	mg	supplier	SOLDERBALL	Tin (Sn)	7440-31-5		6.023		965007	54163
				supplier	SOLDERBALL	Silver (Ag)	7440-22-4		0.218		34993	1964
ENCAPSULATION	M-011 Other inorganic materials	53.759	mg	supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		48.309		898619	-565570
				supplier	MOLDING COMPOUND	Epoxy resin	Proprietary		2.453		45621	22055
				supplier	MOLDING COMPOUND	Phenol resin	Proprietary		2.180		40552	19605
				supplier	MOLDING COMPOUND	Metal Hydroxide	Proprietary		0.545		10138	4901
				supplier	MOLDING COMPOUND	Carbon black	1333-86-4		0.273		5069	2451